APPROVAL SHEET

To：

Customer P/N：

UDE P/N：SB00-ZZ-0001

Description：SFP28 Connector
Right Angle;SMT
Contact Area : 30μ" Gold
Solder Tail : 120μ" min. Matte Tin
Packing with Tape Reel

RoHS

Spec No.	Update Date	Revision
SB0019001-00	2019/7/22	B

Approved	Checked	Prepared

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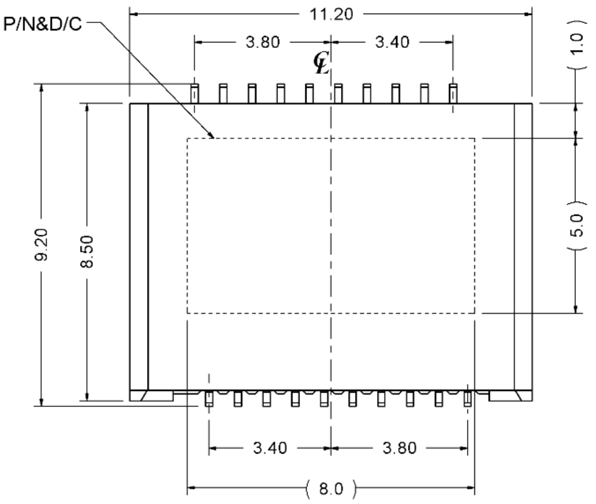
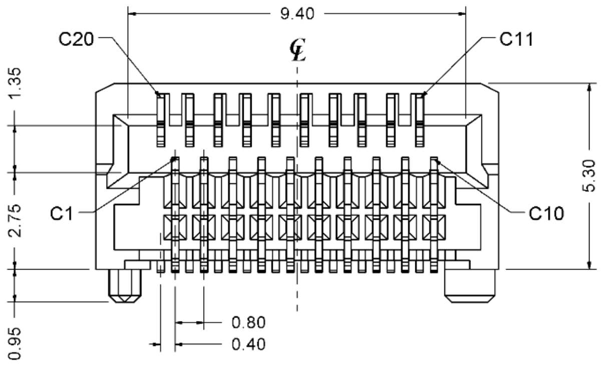
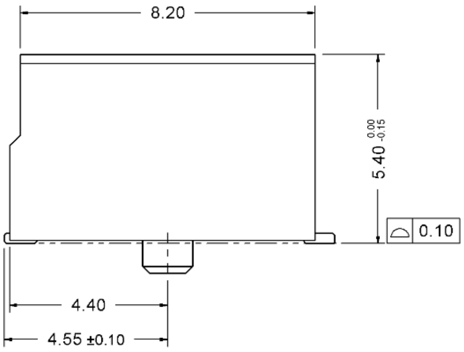
1. MECHANICAL DIMENSION

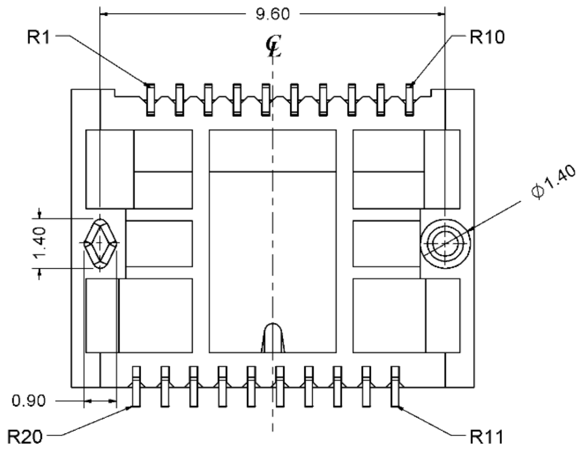
1.1 Product Dimension

General Tolerance :	X.X : ± 0.25 X.XX : ± 0.13





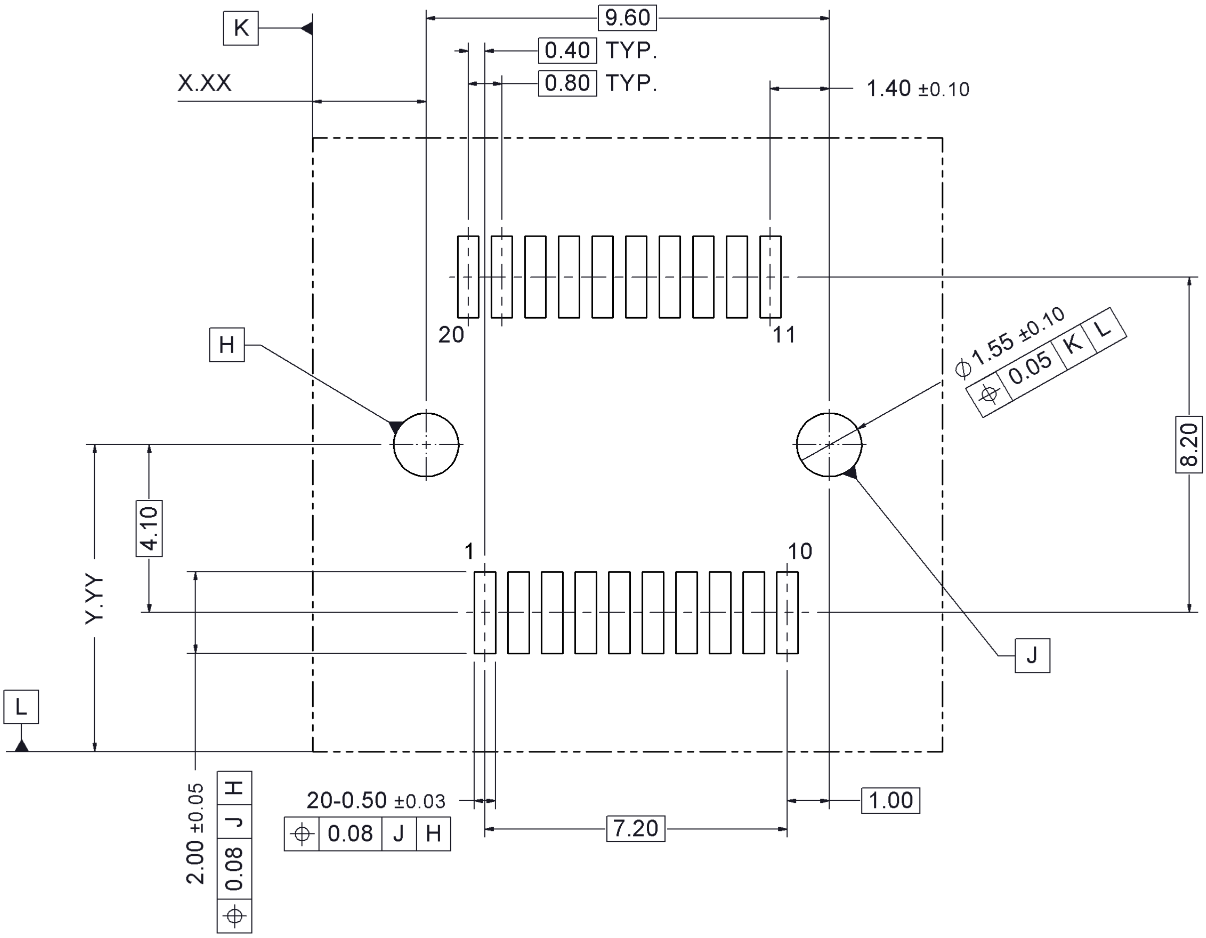




1.2 Recommended PCB Layout

Component Side of Board

All dimension tolerances are ±0.05mm unless otherwise specified



1.3 Packing Information

569 pcs finished goods per reel

10 carries (5690 pcs finished goods) per box

2. REQUIREMENTS

2.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

2.2 Material

2.2.1 Terminal Parts (Underplating : 50μ" min. Nickel overall)

2.2.1.1 Terminal : PH. Bronze, Thickness=0.20mm

Finish : Contact Area : 30μ" Gold

Solder Tail : 120μ" min. Matte. Tin

2.2.2 Plastic Parts

2.2.2.1 Housing : LCP, Black <UL94V-0>

2.3 Operating and Storage Temperature

Operating Temperature : -40℃ to +85℃

Storage Temperature : -20℃ to +85℃

2.4 SFP28 1X Connector specifications

Contact Current Rating: 0.5A (per contact)

Insulation Resistance 1000MΩ min.

Dielectric Withstanding Voltage : 300VDC @1min.

Insertion force : 40N MAX.

Extraction force : 12.5N MAX.

Durability : 100 cycles MIN.

2.5 Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

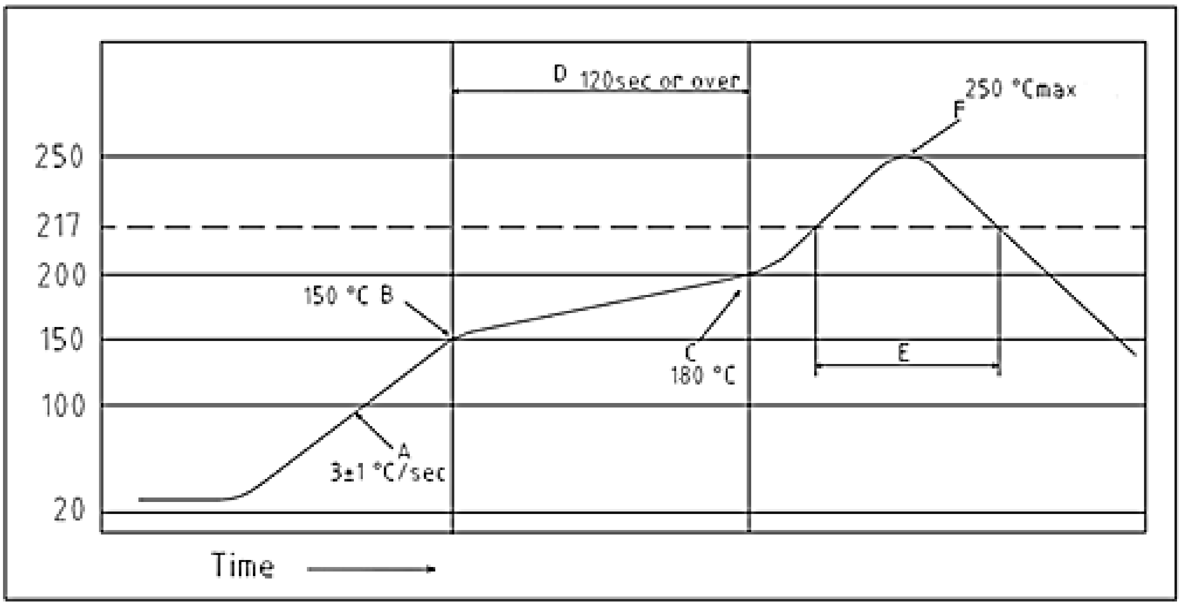
2.6 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage,corrosion and deterioration during shipment and storage.

3. IR REFLOW TEMPERATURE PROFILE

Temperature condition of reflow soldering

Contents	Soldering Condition
A: Increasing speed	3±1 ℃/sec
B: Pre-heat starting Temp	150 ℃
C: Pre-heat ending Temp	180 ℃
D: Pre-heat interval	120 sec or over
E: Over 217 ℃ time	60～150 sec
F: Peak Temperature	250℃ max



Type of lead-free solder should be 96.5Sn-3.0Ag-0.5Cu or 99.3Sn-0.7Cu.

4. Revision History

Issue Date	Revision	Comments	Operator
2019/7/18	A	Initial Release .	Jackson
2019/7/22	B	Modify package quantity .	Jackson